

# AN13762

## Using MIFARE SAM AV3 for NTAG 22x authentication and SUN verification

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Application note

### Document information

Information	Content
Keywords	MIFARE SAM AV3, NTAG 224 DNA, SUN, SDM, CMAC, verification, authentication
Abstract	This application note shows how to use MIFARE SAM AV3 with NTAG 22x DNA for SUN verification and authentication.



## Revision history

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### Revision history

Rev	Date	Description
v.1.0	20221107	Initial version

## 1 Introduction

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MIFARE SAM AV3 ([3]) is a secure element designed to work with MIFARE products like MIFARE DESFire or MIFARE Plus.

As NTAG DNA products use similar crypto functionalities as MIFARE products, MIFARE SAM AV3 can also be used together with NTAG 22x DNA ([1], [2]) for authentication and SUN message verification.

This application note covers the usage of MIFARE SAM AV3 specifically together with NTAG22x DNA products, NTAG 424 DNA is covered in a separate application note [4].

**Note: This application note does not replace any of the relevant data sheets, application notes or design guides.**

Any data, values, cryptograms are expressed as hex string format if not otherwise mentioned, e.g., 0x563412 in hex string format represented as "123456". Byte [0] = 0x12, Byte [1] = 0x34, Byte [2] = 0x56.

## 2 Creating a SAM key entry for usage with NTAG 22x DNA

To support the authentication and SUN message verification, the secret key to be used needs to be injected into the MIFARE SAM AV3 symmetric keystore. This key can be used either diversified or non-diversified.

NTAG 22x DNA needs an AES-128 key of key class "OfflineCrypto".

**Note:** A key of key class "PICC" will not work, as the secure messaging used in NTAG 22x DNA is not natively implemented in MIFARE SAM AV3.

The following example writes an all 00s AES-128 key entry into MIFARE SAM AV3 at KeyEntry 0x01:

Table 1. Preparing the KeyEntries for use with NTAG 22x DNA

Step	Command	Direction	Message	Comment
1	SAM_ChangeKey Entry	>	80C101FF40 00000000000000000000000000000000 00000000000000000000000000000000 00000000000000000000000000000000 000000000000FF20000000000400 FEFE	Inject an AES128 all 00s (default key) key into SAM KeyEntry 0x00. KeyClass is OfflineCrypto, KeyVAEK is set to 0xFE, this means that this key can subsequently be used without Host Authentication on MIFARE SAM AV3. For details refer to <a href="#">[3]</a> .
2	Response	<	9000	Success

### 3 Downloading a key from MIFARE SAM AV3 to NTAG 22x DNA

As the NTAG 22x DNA does not support a secure mechanism for key injection, this process needs to be done in a secure environment, as the key is handled in plain. If a key stored inside a MIFARE SAM AV3 needs to be injected into an NTAG 22x DNA, the key needs to be dumped from the SAM and written into the corresponding memory area in NTAG 22x DNA.

To be able to dump a secret key from MIFARE SAM AV3, the KeyEntry needs to have bit 3 of the ExtSET bytes enabled. This makes the secret key exportable in plain or encrypted form, using the SAM\_DumpSecretKey command. Additionally, in case the key should be used in diversified form, the bit 4 of ExtSET should also be set, to only allow dumping if a diversification input is provided.

Table 2. Secure messaging example

Step	Command	Direction	Message	comment
<b>dump plain</b>				
1	SAM_ChangeKey Entry	>	80C101FF40 00000000000000000000000000000000 00000000000000000000000000000000 00000000000000000000000000000000 000000000000 FF200000010209000000	Load Key into KeyEntry 0x01 of MIFARE SAM AV3. ExtSet bit 3 is enabled, dump of secret key is allowed. (ExtSet = 0x0009)
2	Success	<	9000	
3	SAM_DumpSecret Key	>	80D6000002010000	Dump the secret key in plain
4	Key Data	<	00000000000000000000000000000000 9000	Secret key and status code
<b>dump diversified</b>				
5	SAM_ChangeKey Entry	>	80C101FF40 00000000000000000000000000000000 00000000000000000000000000000000 00000000000000000000000000000000 000000000000 FF200000010219000000	Load Key into KeyEntry 0x01 of MIFARE SAM AV3. ExtSet bit 3 and bit 4 are enabled, dump of secret key is allowed but only in diversified form (ExtSet = 0x0019)
6	Success	<	9000	
7	SAM_DumpSecret Key	>	80D602000901000411223344556600	Dump the secret key in plain, diversified form (P1 = 0x02), div input = 04112233445566
8	Key Data	<	2360D14689E17C7AA9821665E68 A0099 9000	Diversified secret key and status code

The dumped key needs to be written inside the AES Key\_x area inside the NTAG 22x DNA memory. This process is described in the data sheets [1] and [2].

## 4 Authenticating NTAG 224 DNA

There is no dedicated command for Authenticating NTAG 224 DNA on MIFARE SAM AV3 available. Therefore, authentication is done "by hand" using the offline crypto functionalities on MIFARE SAM AV3. There is no AES-128 authentication available on NTAG 223 DNA.

**Table 3. Authenticating NTAG 224 DNA**

Step	Command	Direction	Message	Comment
1	ActivateOffline Key	>	80010000020100	Activate the secret key
2	Response	<	9000	success
3	Authenticate part 1	>	1A00	First Part of Authenticate command sent to NTAG 224 DNA
4	E(Kx,RndB)	<	AF37B7F49CD707F8D8E29 DDEC256912187	0xAF + E(Kx,RndB)
5	LoadIV	>	8071000010 00000000000000000000000000000000	Sets the SAM's IV to all 0x00s
6	Response	<	9000	success
7	SAM_Decipher Offline_Data	>	800D00001037B7F49CD707F8D8E29 DDEC25691218700	Decrypts the encrypted RndB
8	RndB	<	D220B067DE955EFA0A24623F4F216 AC59000	RndB
9	GetRandom	>	8084000010	Generates 16 byte random data as RndA
10	RndA	<	07F8AAE1B62FB3930977BDCD16157 E8B9000	RndA
11	LoadIV	>	8071000010 00000000000000000000000000000000	Sets the SAM's IV to all 0x00s
12	Response	<	9000	success
13	SAM_Encipher Offline_Data	>	800E00002007F8AAE1B62FB3930977 BDCD16157E8B20B067DE955EFA0 A24623F4F216AC5D200	Encrypts the concatenation of RndA and RndB' (RndB' is the rotation of RndB by one byte)
14	E(Kx,RndA  RndB')	<	66FDB31BFD79F3C02E17C44 FCDB7466B669DFA2F986F568725703 DDF47D0243D9000	Encrypted RndA    RndB'
15	Authenticate part 2	>	AF66FDB31BFD79F3C02E17C44 FCDB7466B669DFA2F986F568725703 DDF47D0243D	Authenticate part 2 sent to NTAG 224 DNA
16	E(Kx,RndA')	<	002D9194C800DBA0C4B8A85 CACD54F6568	0x00 (success) and encrypted RndA'
17	LoadIV	>	8071000010 00000000000000000000000000000000	Sets the SAM's IV to all 0x00s
18	Response	<	9000	success
19	SAM_Decipher Offline_Data	>	800D0000102D9194C800DBA0C4B8 A85CACD54F656800	Decrypts the encrypted RndA'

Table 3. Authenticating NTAG 224 DNA...continued

Step	Command	Direction	Message	Comment
20	RndA'	<	F8AAE1B62FB3930977BDCD16157E8 B079000	RndA'

## 5 SUN message verification

For SUN message verification, the same key settings in MIFARE SAM AV3 are required as for authentication.

First of all, the SUN message needs to be read from the NTAG 22x DNA. This can be done in several ways, either the message is conveyed as NDEF content, or the memory is read with a READ command at the position where the mirroring is pointing to. After this, the SUN part needs to be converted back into hex data from the ASCII representation, and can be sent to the MIFARE SAM AV3 for verification.

The SUN message is always a concatenation of the UID (14 byte ASCII), the NFC\_CTR (6 byte ASCII) and the CMAC (16 byte ASCII), separated by an "x" (0x78) character. The total length is 39 bytes (ASCII).

Table 4. Authenticating NTAG 224 DNA

Step	Command	Direction	Message	Comment
1	Read page 0x39	>	3039	read configuration page to obtain mirror location
2	content of page 0x39 - 0x3C	<	<b>8000094</b> C90000000000000000000000	CFG_B0 → 0x80: Mirroring enabled, MIRROR_BYTE = 00b. MIRROR_PAGE → 0x09
3	FastRead page 0x09 until 0x13	>	3A0913	read pages 0x09(MIRROR_PAGE) until page 0x13 (MIRROR_PAGE + 10). This will result in 44 bytes of data. The SUN message is always 39 bytes long (ASCII), hence this command will for sure cover the whole SUN message
4	SUN message in ASCII read out of the memory	<	30344234424634413033313039307830 30303030357832463544373630363534 453931413442000030303030	SUN message in ASCII representation
5	UID (ASCII)	=	3034423442463441303331303930	
6	UID (hex)	=	04B4BF4A031090	
7	NFC_CTR (ASCII)	=	303030303035	
8	NFC_CTR (hex)	=	000005	
9	CMAC (ASCII)	=	32463544373630363534453931413442	
10	CMAC (hex)	=	2F5D760654E91A4B	
11	ActivateOffline Key	>	80010000020100	Activate the secret key
12	Response	<	9000	success
13	SAM_GenerateMAC	>	807C00800A04B4BF4 A03109000000500	Generate CMAC over UID and NFC_CTR in hex values
14	SAM Response	<	2F5D760654E91A4B9000	CMAC + success code
15	compare CMACs	=	2F5D760654E91A4B = 2F5D760654 E91A4B	SUN Message verified

In case the message is retrieved via NDEF, steps 1 to 4 are a bit different, but from step 5 onwards the process is the same. For above example, the NDEF message would look like this: "nxp.com/data=04B4BF4A031090x000005x2F5D760654E91A4B". This



message already contains UID, NFC\_CTR and CMAC, which can be used for the verification.

The necessary steps to set up the SUN feature are described in [\[1\]](#) and [\[2\]](#).

## 6 Abbreviations

Table 5. Abbreviations

Acronym	Description
AES	Advanced Encryption Standard
NDEF	NFC Data Exchange Format
NFC	Near Field Communication
SAM	Secure Application Module
SE	Secure Element
SUN	Secure Unique NDEF

## 7 References

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- [1] **Data sheet NTAG 224 DNA** - [NT2H2421G0](#) NTAG 224 DNA - NFC T2T compliant IC
- [2] **Data sheet NTAG 224 DNA** - [NT2H2421G0](#) NTAG 223 DNA - NFC T2T compliant IC
- [3] **Data sheet MIFARE SAM AV3** - DS3235xx - available via [Secure Files on NXP.com](#)
- [4] **Application note** - [AN12697](#) MIFARE SAM AV3 for NTAG 424 DNA

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